

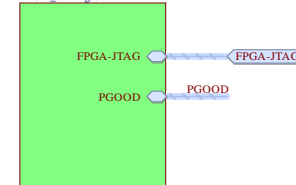
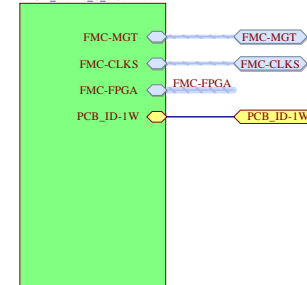
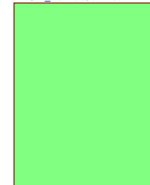
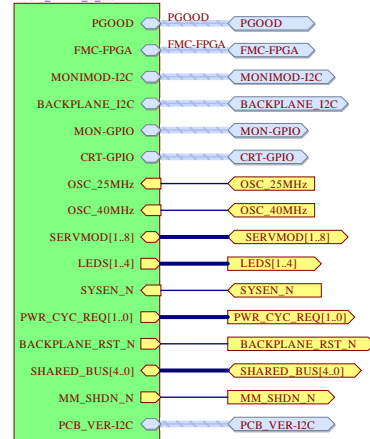
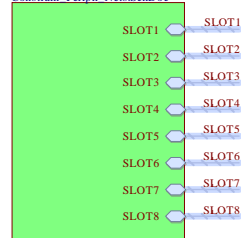
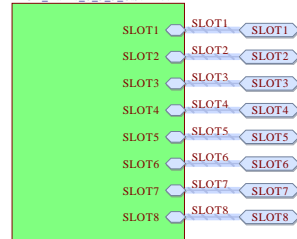
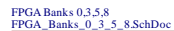
Copyright CERN 2020.

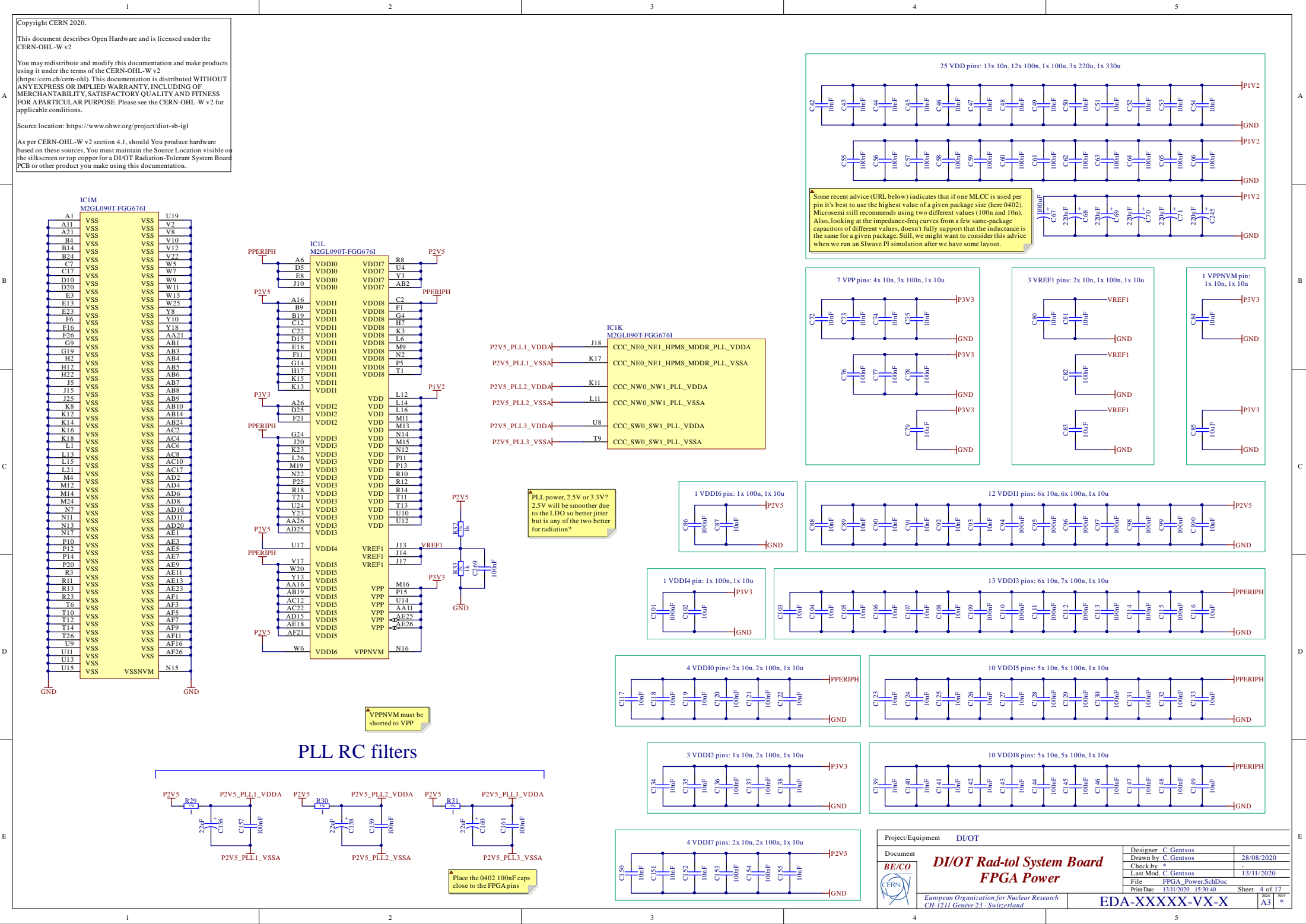
This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-igl>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.





Copyright CERN 2020.

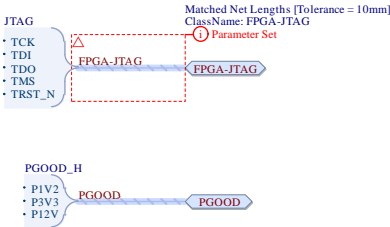
This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

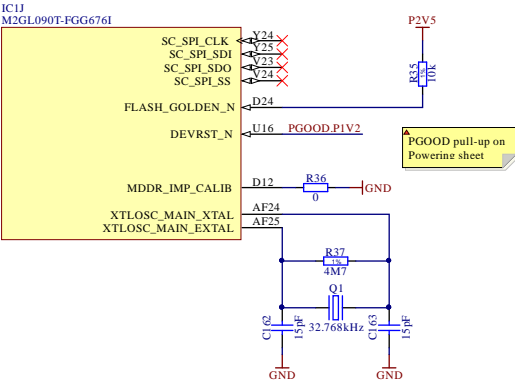
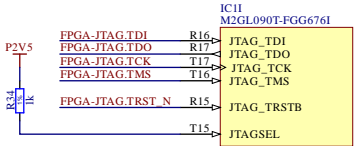
Source location: <https://www.ohwr.org/project/diot-sb-igl>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

Parts powered by 2.5V



The JTAG and configuration pins are referred to as Bank 4



Project/Equipment		DI/OT	
Document		Designer	C. Gentsos
		Drawn by	C. Gentsos
		Check by	*
		Last Mod.	C. Gentsos
		File	FPGA_Config.SchDoc
		Print Date	13/11/2020 15:30:40
		Sheet	5 of 17
		Size	A3
		Rev	*

DI/OT Rad-tol System Board
FPGA Configuration and reset

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

Copyright CERN 2020.

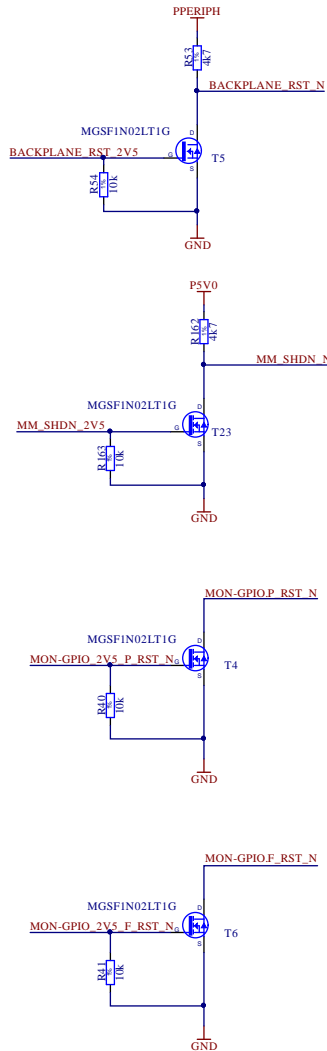
This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

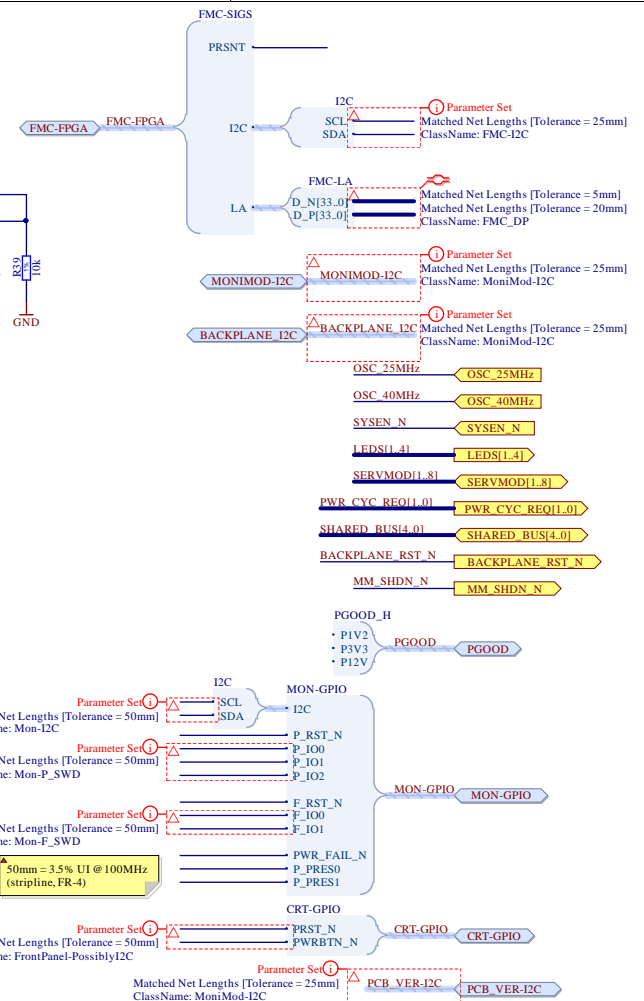
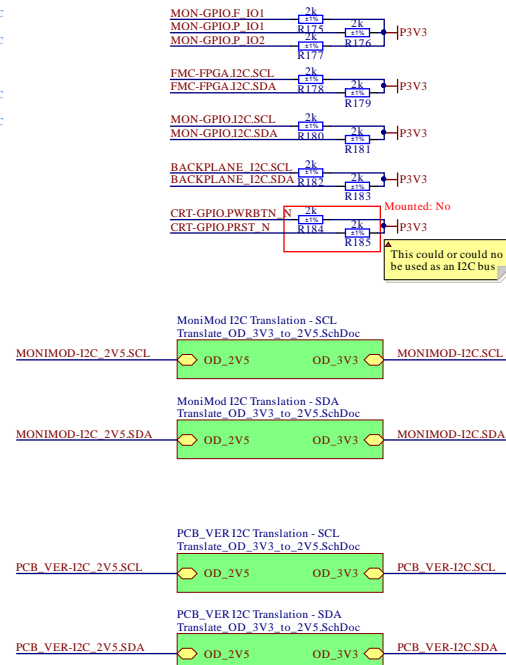
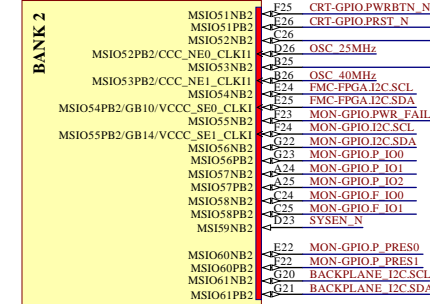
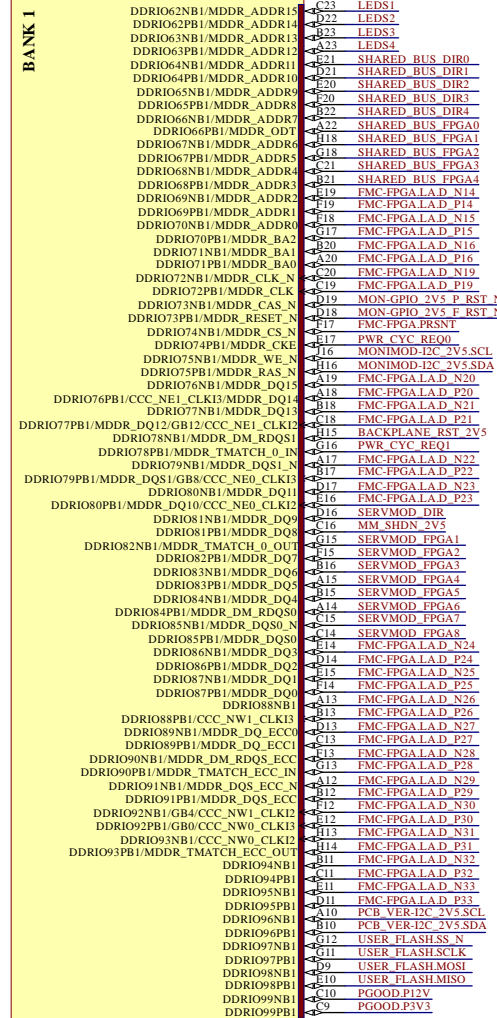
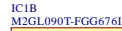
Source location: <https://www.ohwr.org/project/diot-sb-igl>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

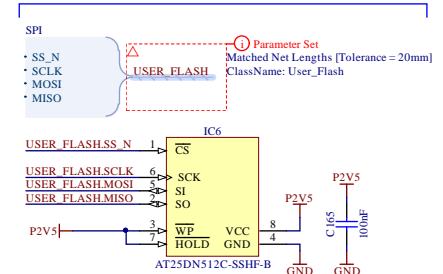
Level translators





Bank 1 powered by 2.5V, Bank 2 by 3.3V



SPI Flash



Project/Equipment		DI/OT	
Document	<div>BE/CO</div> <div></div> <div>European Organization for Nuclear Research CH-1211, Geneva 23 - Switzerland</div>	Designer C. Gentsos	
<div></div>		Drawn by C. Gentsos 28/08/2020	
		Check by + -	
		Last Mod. C. Gentsos 12/11/2020	
		File Name FPGA Banks 1, 2 SchDoc	
	Print Date 13/11/2020 15:30:42	Sheet 7 of 17	A3
		EDA-XXXXXX-VX-X	

Copyright CERN 2020.

This document describes Open Hardware and is licensed under the CERN-OHL-W v2

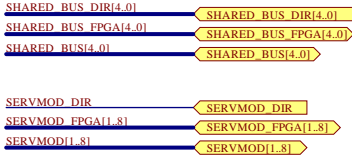
You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-ig1>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

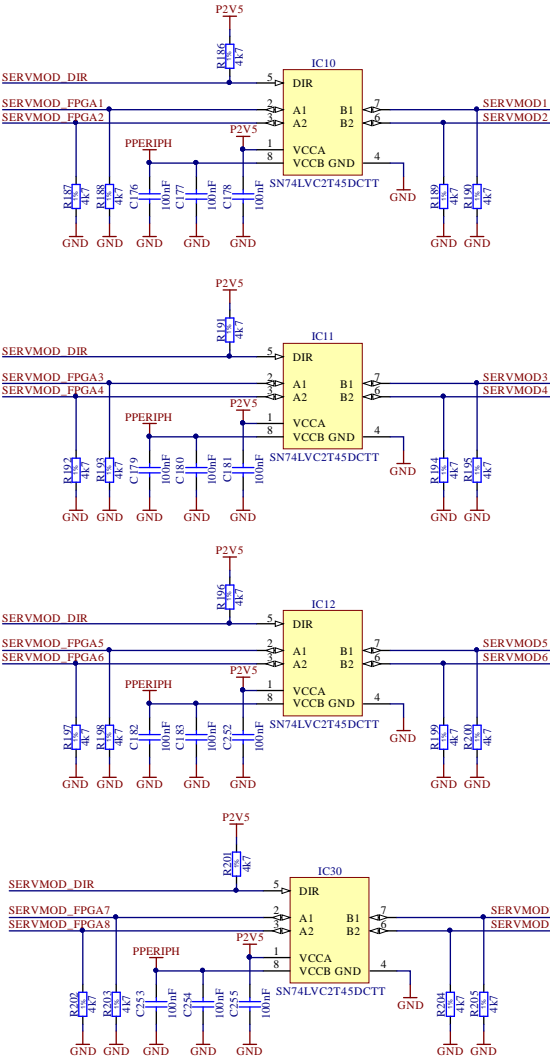
Maybe that's nit-picking but according to the datasheet, VCCB must be ramped-up with or after VCCA. If VCCB is set to 3V3 its ramp-up will come just slightly ahead of VCCA but not by much.

Bi-directional level translators



We used to have both I/Os connected together for more drive strength but at 3.3V that might be too much: each pin can already source or sink 24mA.

At 2.5V and 1.8V, however, that quickly drops to 8mA and 4mA, respectively. For applications with low PPERIPH, the optionally-mounted 0R resistors can provide the double drive strength, if necessary.



Copyright CERN 2020.

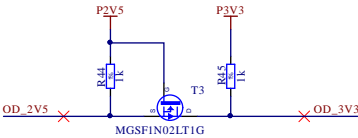
This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.



Source location: <https://www.ohwr.org/project/diot-sb-ig1>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

Level translators for open-drain interfaces as described in AN10441



Project/Equipment		DI/OT	
Document		Designer	C. Gentsos
		Drawn by	C. Gentsos
		Check by	*
		Last Mod.	C. Gentsos
		File	Translate_OD_3V3_to_2V5_SchDoc
		Print Date	13/11/2020 15:30:43
		Sheet	9 of 17
		Size	A3
		Rev	*



DI/OT Rad-tol System Board

Open-drain Voltage Translators

European Organization for Nuclear Research

CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

Copyright CERN 2020.

This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

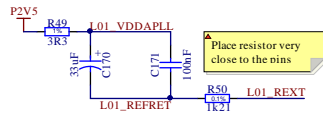
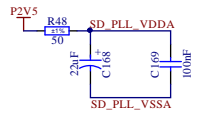
Source location: <https://www.ohwr.org/project/diot-sb-igl>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

Banks powered by 2.5V

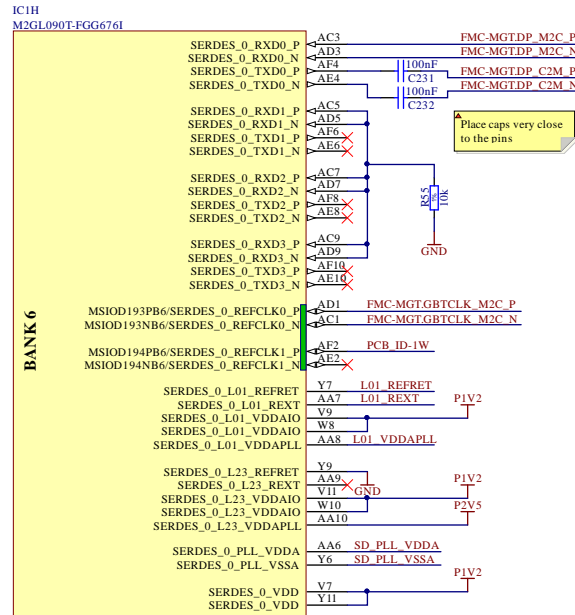


TODO: requested 0402 symbols, use them when ready

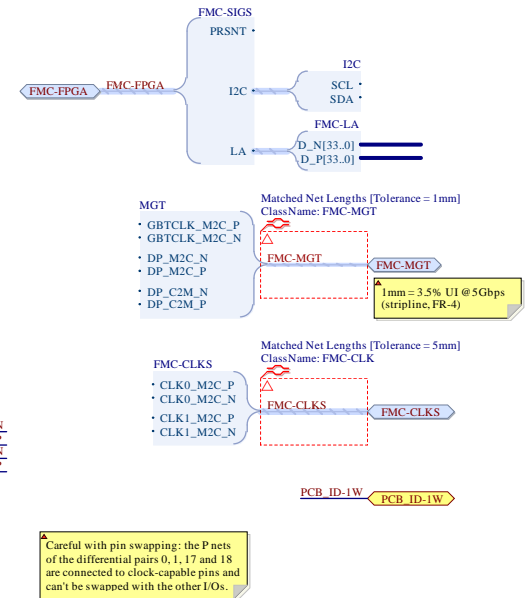
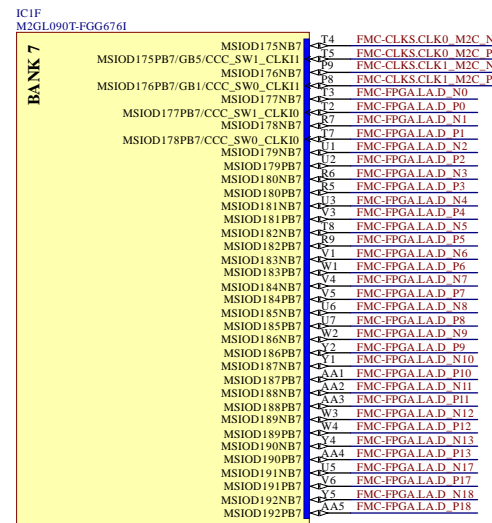



Application Note AC393, p. 5

TODO: requested 0402 symbols, use them when ready



Place caps very close to the pins



Project/Equipment		DI/OT			
Document BE/CO 	DI/OT Rad-tol System Board FPGA I/O Banks B6, B7		Designer	C. Gentsos	
			Drawn by	C. Gentsos	28/08/2020
			Checked by	+	
			List Mod.	C. Gentsos	12/11/2020
			File	FPGA_Banks_6_7_SchDoc	
		Print Date	13/11/2020 15:30:43	Sheet	10 of 17
European Organization for Nuclear Research CH-1211 Geneva 23, Switzerland		EDA-XXXX-VX-X A3		100%	

Copyright CERN 2020.

This document describes Open Hardware and is licensed under the CERN-OHL-W v2

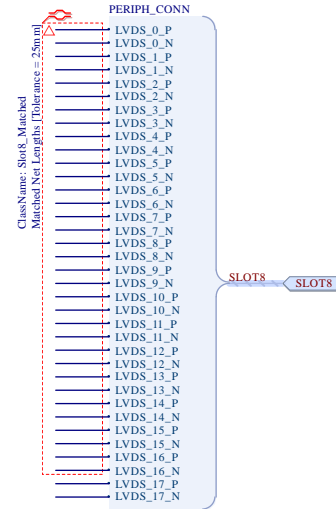
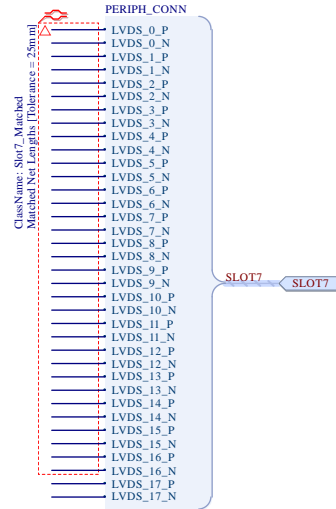
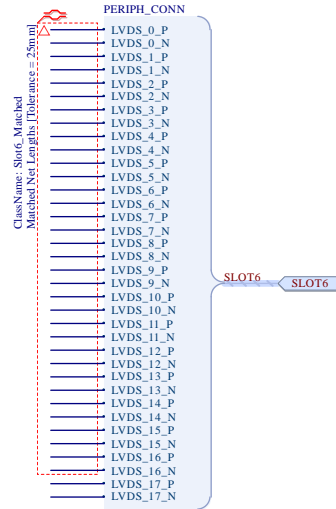
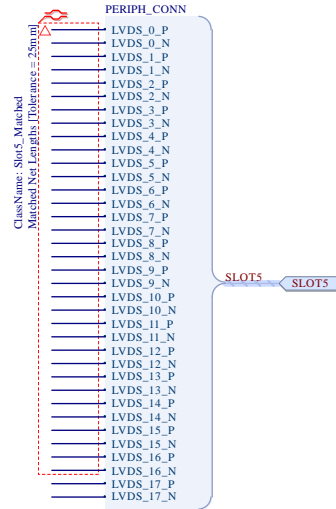
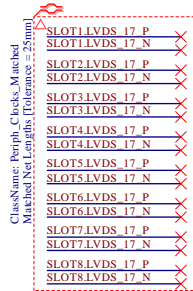
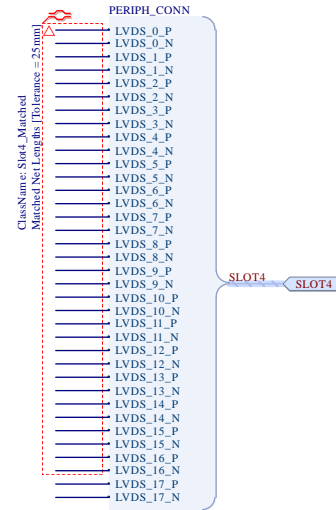
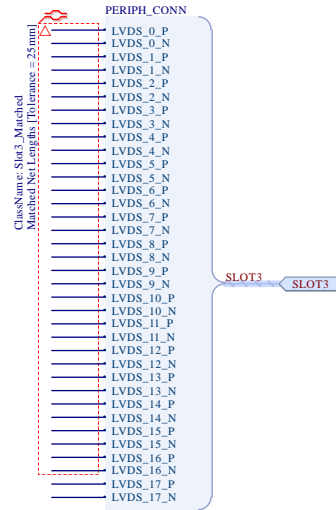
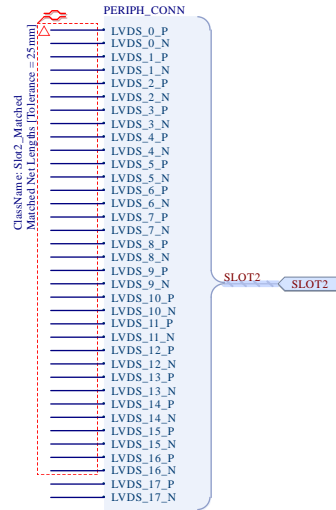
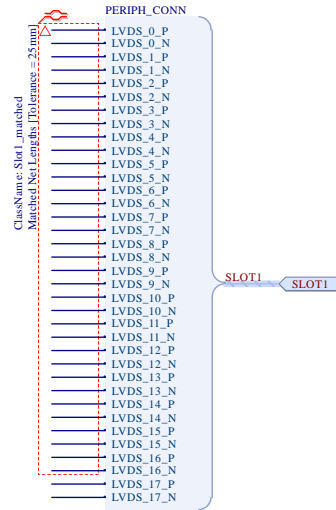
You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-igl>

As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

The diff. pairs that go to each peripheral board are length-matched, excluding the clock-capable pair

The clock-capable pairs are length-matched between the different peripheral boards, instead



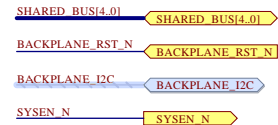
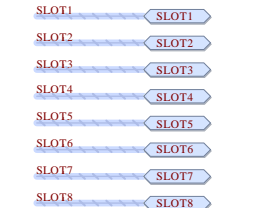
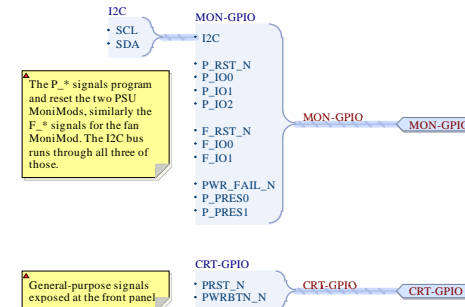
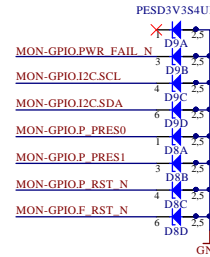
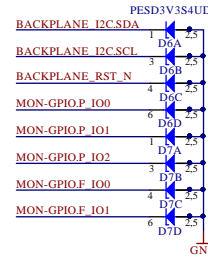
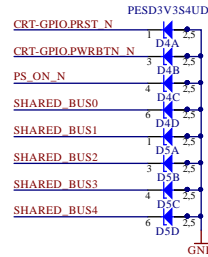
Copyright CERN 2020.

This document describes Open Hardware and is licensed under the CERN-OHL-W v2

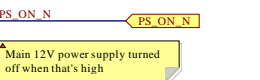
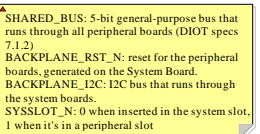
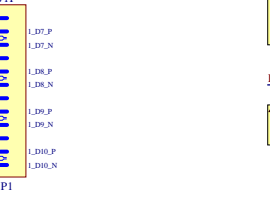
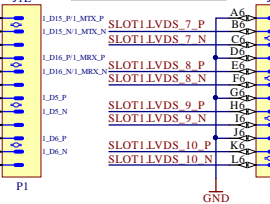
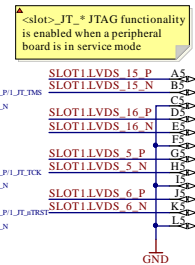
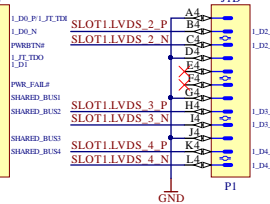
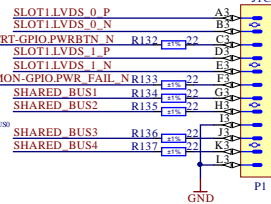
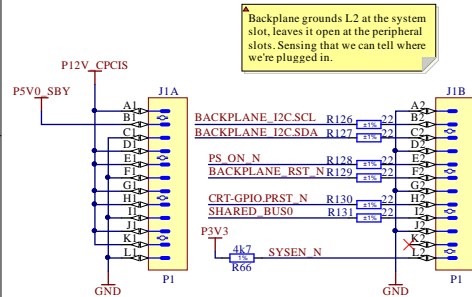
You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-igl>


As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.



▲ All the nets that are exposed to the front panel, the power backplane, or that run through all the peripheral boards, are protected

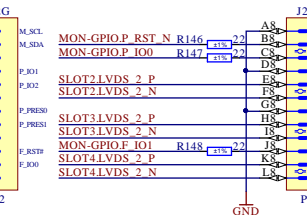
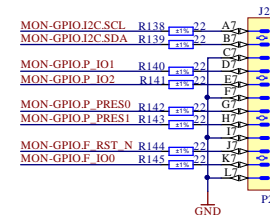
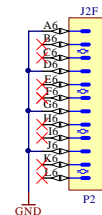
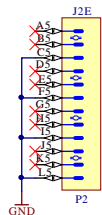
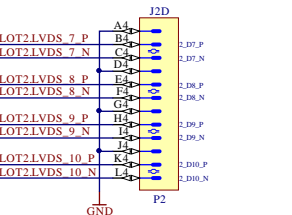
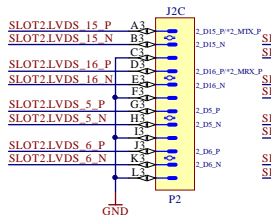
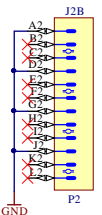
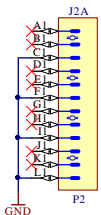


P1 Connector

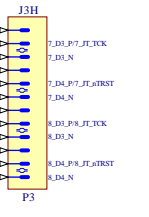
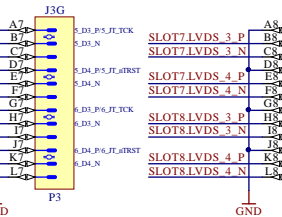
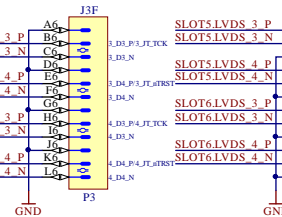
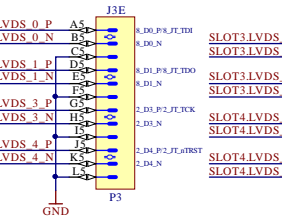
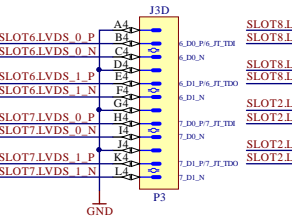
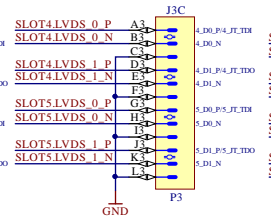
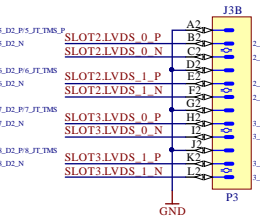
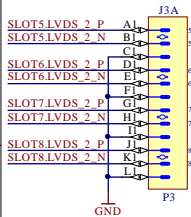
 <slot>_JT_* JTAG functionality is enabled when a peripheral board is in service mode


**<slot>_MTX / <slot>_MRX
signals can be connected to
MGT transceivers on the
non-rad-tol system board**

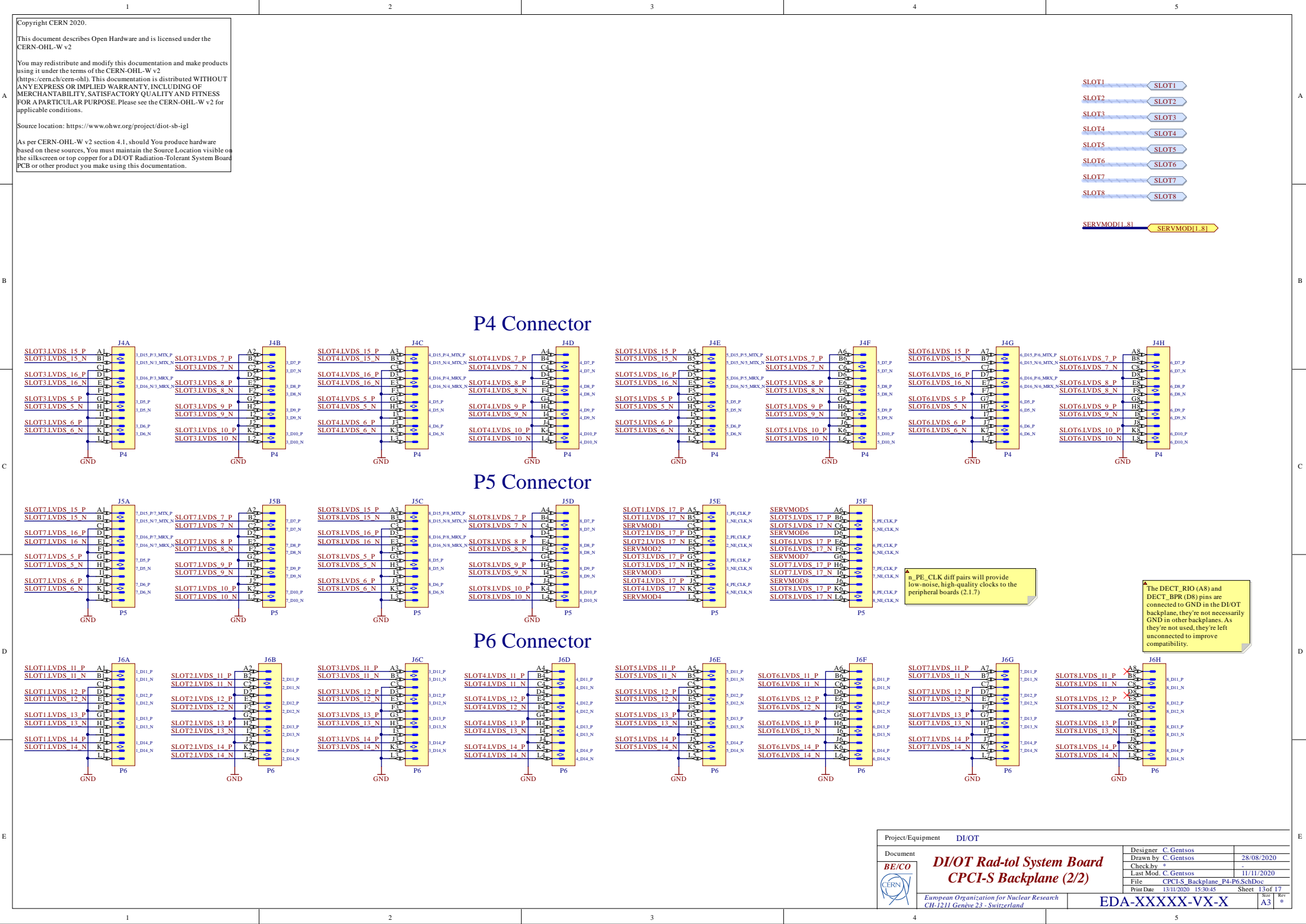
P2 Connector



P3 Connector



Project/Equipment		DI/OT	
Document		Designer: C. Gentsos Drawn by: C. Gentsos Check by: - Last Mod.: C. Gentsos Date: 28/08/2020	
		DI/OT Rad-tol System Board CPCI-S Backplane (1/2)	
European Organization for Nuclear Research CH-1211, Genève 23 - Switzerland		File CPCI-S Backplane - P1-P3 Sch/Doc	Print Date 13/11/2020 15:30:44
		Sheet	12 of 17 A3
		EDA-XXXXX-VX-X	



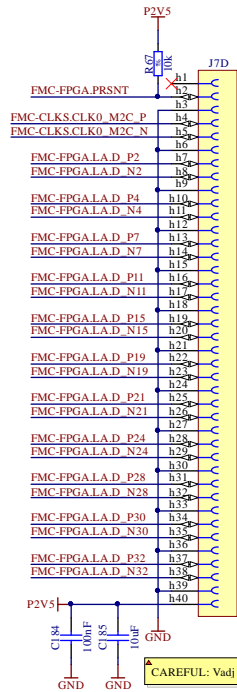
Copyright CERN 2020.

This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-ig1>

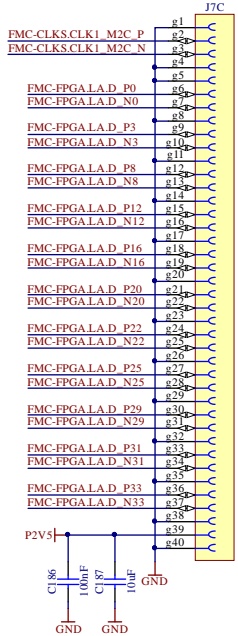
As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.



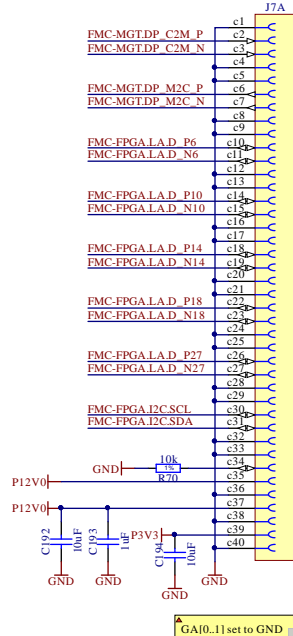
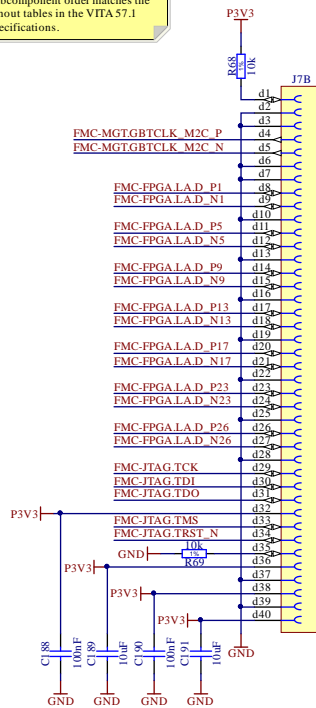
VREF is unused

Only _P pins are actually clock-compatible on the FPGA

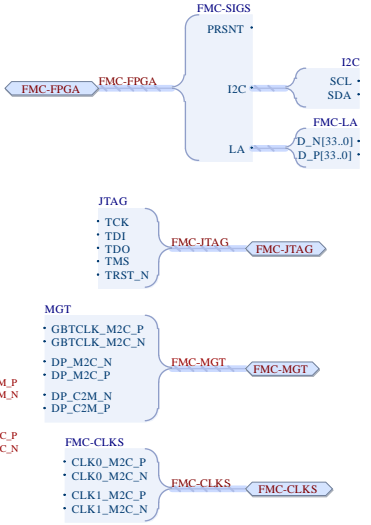
CAREFUL: Vadj is fixed at 2.5V



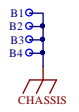
Subcomponent order matches the pinout tables in the VITA 57.1 specifications.



GA[0..1] set to GND



Mounting holes



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by *	
		Last Mod. C. Gentsos	
		File FMC_SchDoc	
		Print Date 13/11/2020 15:30:46	
		Sheet 14 of 17	
		A3	

Project/Equipment: DI/OT

Document: BE/CO

CERN

DI/OT Rad-tol System Board FMC

European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

14 of 17

A3

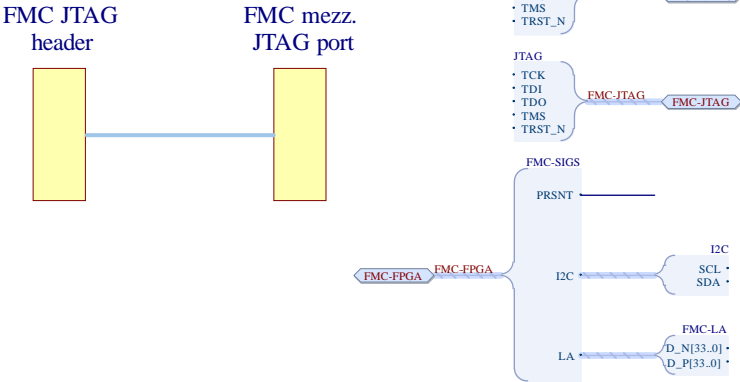
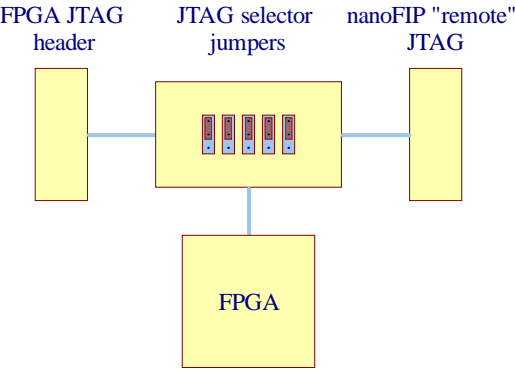
Copyright CERN 2020.

This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-ig1>

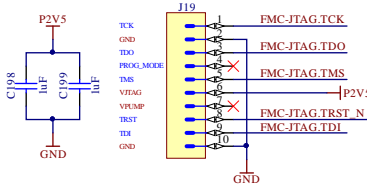
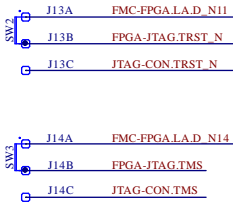
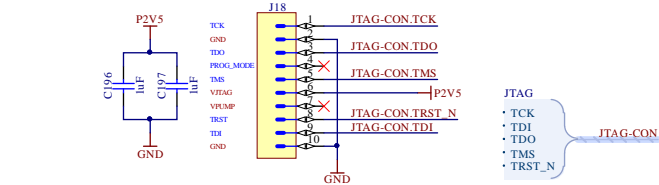
As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.



FPGA JTAG header

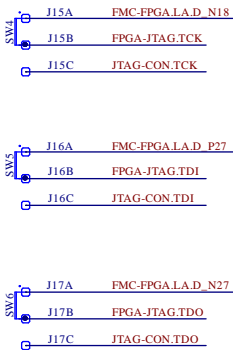
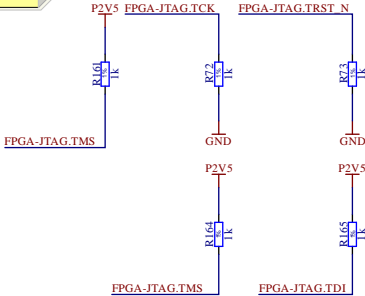
FPGA JTAG selector

FMC JTAG header

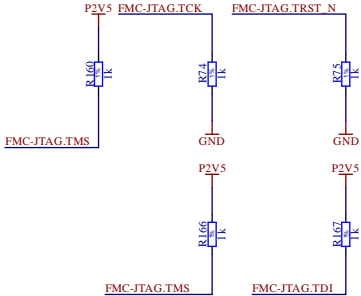


Don't confuse this with the nanoFIP JTAG, this is just to provide an easily accessible JTAG connector to program the FMC card

In the Igloo2 evaluation board they use HTST-105-01-L-DV-A but there doesn't seem to be any difference.



Select between connecting the FPGA JTAG interface to the header or the nanoFIP interface for remote programming



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by *	
		Last Mod. C. Gentsos	
		File JTAG_SchDoc	
		Print Date 13/11/2020 15:30:46	
		Sheet 15 of 17	
		Size A3	
		Rev *	

DI/OT Rad-tol System Board
JTAG Chains

European Organization for Nuclear Research
CH-1211 Genève 23 - Switzerland

EDA-XXXXX-VX-X

Copyright CERN 2020.

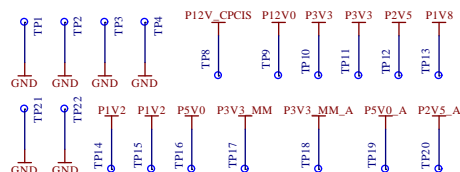
This document describes Open Hardware and is licensed under the CERN-OHL-W v2

You may redistribute and modify this documentation and make products using it under the terms of the CERN-OHL-W v2 (<https://cern.ch/cern-ohl>). This documentation is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MERCHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the CERN-OHL-W v2 for applicable conditions.

Source location: <https://www.ohwr.org/project/diot-sb-igl>

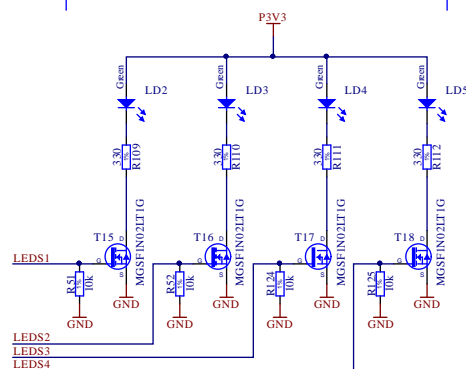
As per CERN-OHL-W v2 section 4.1, should You produce hardware based on these sources, You must maintain the Source Location visible on the silkscreen or top copper for a DI/OT Radiation-Tolerant System Board PCB or other product you make using this documentation.

Power rail test points

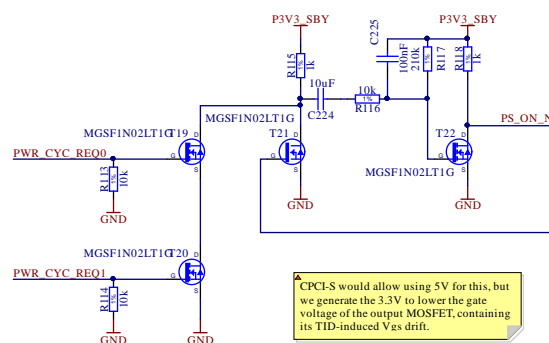


Place Test Points on top layer

User LEDs

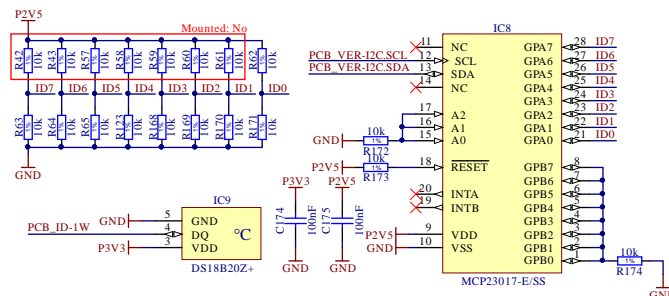


Power cycle pulse generator

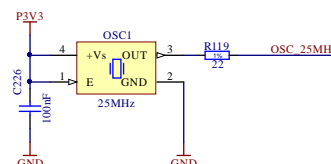


▲ CPCI-S would allow using 5V for this, but we generate the 3.3V to lower the gate voltage of the output MOSFET, containing its TID-induced V_{gs} drift.

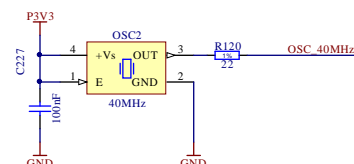
Board version encoding and ID



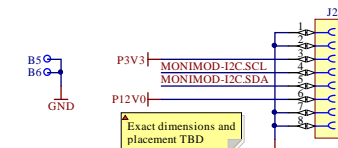
25MHz oscillator



40MHz oscillator

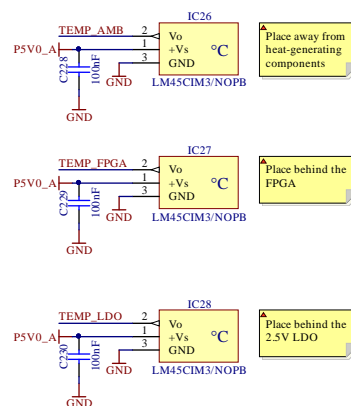


Expansion pin header



Exact dimensions and placement TBD

Temp sensors

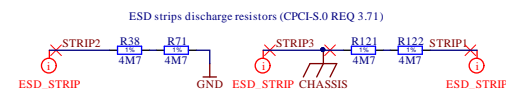


Place away from heat-generating components

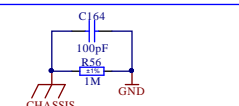
Place behind the
FPGA

Place behind the 2.5V LDO

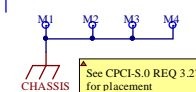
ESD Protection



Chassis-GND connection




Front panel
mounting holes



See CPCI-S.0 REQ 3.2
for placement

Fiducials



Project/Equipment		D/I/O		Designer C. Gentosos			
Document		D/I/O Rad-tol System Board		Drawn by C. Gentosos		28/08/2020	
BE/CO		Miscellaneous		Checked by +			
				Last Mod. C. Gentosos		11/11/2020	
European Organization for Nuclear Research				File Top_Misc.SchDoc			
CERN				Print Date 13/11/2020 15:30:47		Sheet 17 of 17	
				EDA XXXX-XX-X		A3	